



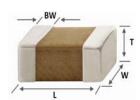


● Supplier : Samsung Electro-Mechanics ● Samsung P/N : CL10B152KB8WPNC

● AEC-Q200 Qualified

A. Dimension

Dimension



Size	0603 inch		
L	1.60±0.10 mm		
W	0.80±0.10 mm		
Т	0.80±0.10 mm		
BW	0.30±0.20 mm		

B. Samsung Part Number

<u>CL</u>	<u>10</u>	<u>B</u>	<u>152</u>	<u>K</u>	<u>B</u>	<u>8</u>	<u>W</u>	<u>P</u>	<u>N</u>	<u>C</u>
1	2	3	4	(5)	6	⑦	8	9	10	11

① Series	Samsung Multi-layer Ceramic Capacitor		
② Size	0603 (inch code)	L: 1.60±0.10 mm	W :0.80±0.10 mm
3 Dielectric	X7R	8 Inner electrode	Ni, Open Mode Design
Capacitance	1.5 nF	Termination	Metal-Epoxy
⑤ Capacitance	± 10%	Plating	Sn 100% (Pb Free)
tolerance		Product	Automotive
Rated Voltage	50 V	Special code	Normal
7 Thickness	0.80±0.10 mm	1 Packaging	Cardboard Type, 7" Reel

C. Reliability Test and Judgement condition

A AL 1 1 1 1				
Appearance : No abnormal exterior appearance	Unpowered, 1,000hrs @ Max. temperature			
Capacitance Change Within ±10 %	Measurement at 24±2hrs after test conclusion			
Tan δ :0.03 max.				
IR :More than 10,000 MΩ or 500 MΩ×μF	Initial Measurement 2*			
Whichever is smaller	Final Measurement 3*			
Appearance : No abnormal exterior appearance	1,000Cycles			
Capacitance Change Within ±10 %	Initial Measurement 2*			
Tan δ :0.03 max.	Final Measurement 3*			
IR : More than 10,000 $^{\mathrm{M}\Omega}$ or 500 $^{\mathrm{M}\Omega}\times\mu$	Measurement at 24±2hrs after test conclusion			
Whichever is smaller	1 cycle condition : -55+0/-3 °C (30±3min) → Room Temp. (1min)			
	→ 125+3/-0°C(30±3min) → Room Temp. (1min)			
No Defects or abnormalities	Per EIA 469			
Appearance : No abnormal exterior appearance	1,000hrs 85℃/85%RH, Rated Voltage and 1.3~1.5V,			
Capacitance Change Within ±12.5 %	Add 100kohm resistor			
Tan δ :0.035 max.	Initial Measurement 2*			
IR :More than 500 № or 25 №×µF	Final Measurement 4*			
Whichever is smaller	Measurement at 24±2hrs after test conclusion			
	The charge/discharge current is less than 50mA.			
Appearance : No abnormal exterior appearance	1,000hrs @ 125℃, 200% Rated Voltage,			
Capacitance Change Within ±12.5 %	Initial Measurement 2*			
Tan δ :0.035 max.	Final Measurement 4*			
IR :More than 1,000 ^{MΩ} or 50 ^{MΩ} ×μF	Measurement at 24±2hrs after test conclusion			
Whichever is smaller	The charge/discharge current is less than 50mA.			
	Tan δ : 0.03 max. IR: More than 10,000 MΩ or 500 MΩ×μF Whichever is smaller Appearance: No abnormal exterior appearance Capacitance Change Within ±10 % Tan δ : 0.03 max. IR: More than 10,000 MΩ or 500 MΩ×μF Whichever is smaller No Defects or abnormalities Appearance: No abnormal exterior appearance Capacitance Change Within ±12.5 % Tan δ : 0.035 max. IR: More than 500 MΩ or 25 MΩ×μF Whichever is smaller Appearance: No abnormal exterior appearance Capacitance Change Within ±12.5 % Tan δ : 0.035 max. IR: More than 1,000 MΩ or 50 MΩ×μF			

	Performance	Test condition					
External Visual	No abnormal exterior appearance	Microscope ('10)					
Physical Dimension	Within the specified dimensions	Using The calipers					
Mechanical Shock	Appearance : No abnormal exterior appearance	Three shocks in each direction should be applied along					
	Capacitance Change Within ±10 %	3 mutually perpendicular axes of the test specimen (18 shocks)					
	Tan δ, IR : Initial spec.	Peak value Duration Wave Velocity					
		1,500G 0.5ms Half sine 4.7m/sec					
		Initial Measurement 2*					
		Final Measurement 5*					
Vibration	Appearance : No abnormal exterior appearance	5g's for 20min., 12cycles each of 3 orientations,					
	Capacitance Change Within ±10 %	Use 8"×5" PCB 0.031" Thick 7 secure points on one long side					
	Tan δ, IR : Initial spec.	and 2 secure points at corners of opposite sides. Parts mounted					
	·	within 2" from any secure point. Test from 10~2,000Hz.					
		Initial Measurement 2*					
		Final Measurement 5*					
Resistance to	Appearance : No abnormal exterior appearance	preheating: 150°C for 60~120 sec.					
Solder Heat	Capacitance Change Within ±10 %	Solder pot : 260±5 ℃, 10±1sec.					
	Tan δ, IR : Initial spec.	Initial Measurement 2*					
		Final Measurement 3*					
ESD	Appearance : No abnormal exterior appearance	AEC-Q200-002 or ISO/DIS10605					
	Capacitance Change Within ±10 %	Initial Measurement 2*					
	Tan δ, IR : Initial spec.	Final Measurement 4*					
Solderability	95% of the terminations is to be soldered	a) Preheat at 155 °C for 4 hours, Immerse in solder for 5s at 245±5 °C					
	evenly and continuously	b) Steam aging for 8 hours, Immerse in solder for 5s at 245±5 °C					
		c) Steam aging for 8 hours, Immerse in solder for 120s at 260±5 °C					
		solder : a solution ethanol and rosin					
Electrical	Capacitance : Within specified tolerance	*A capacitor prior to measuring the capacitance is heat treated at					
Characterization	Tan δ :0.025 max.	150 +0/-10 ℃ for 1hour and maintained in ambient air for 24±2 hours					
	IR(25℃): More than 10,000 № or 500 №×μF	The Capacitance / D.F. should be measured at 25 ℃,					
	Whichever is smaller	1 kHz ± 10%, 1 ± 0.2 Vrms					
	IR(125℃) More than 1,000 № or 10 №×μF	I.R. should be measured with a DC voltage not exceeding					
	Whichever is smaller	Rated Voltage @25℃, @125℃ for 60~120 sec.					
	Dielectric Strength	Dielectric Strength : 250% of the rated voltage for 1~5 seconds					
Board Flex	Appearance : No abnormal exterior appearance	Bending to the limit, 3 mm for 60 seconds 1*					
	Capacitance Change Within ±10 %	Initial Measurement 2*					
		Final Measurement 5*					
Terminal	Appearance : No abnormal exterior appearance	10 N, for 60 sec.					
Strength(SMD)	Capacitance Change Within ±10 %	Initial Measurement 2*					
		Final Measurement 5*					
Beam Load	Destruction value should be exceed 20 N	Beam speed: 0.5±0.05 mm/sec					
Temperature	X7R						
Characteristics	From -55 $^{\circ}$ C to 125 $^{\circ}$ C, Capacitance change shou	lld be within ±15%					

D. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260 +0/-5°C, 30sec.), Meet IPC/JEDEC J-STD-020 D Standard

- *1 : The figure indicates typical specification. Please refer to individual specifications.
- *2 : Initial measurement : Perform a heat treatment at 150 +0/-10 $^{\circ}\mathrm{C}$ for one hour after soldering process. and then let sit for 24±2 hours at room temperature. Perform the initial measurement.
- $^{\star}3$: Final measurement : Let sit for 24 \pm 2 hours at room temperature after test conclusion, then measure.
- *4 : Final measurement : Perform a heat treatment at 150 +0/-10 °C for one hour after soldering process. and then let sit for 24±2 hours at room temperature. Perform the initial measurement.
- *5 : Final measurement : Let measure within 24 hours at room temperature after test conclusion.



A Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

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- ② Medical equipment
- 3 Military equipment
- 4 Disaster prevention/crime prevention equipment
- ⑤ Power plant control equipment
- 6 Atomic energy-related equipment
- ① Undersea equipment
- 8 Traffic signal equipment
- Data-processing equipment
- @ Electric heating apparatus, burning equipment
- Safety equipment
- @ Any other applications with the same as or similar complexity or reliability to the applications